



# Product Change Notification

**Change Notification #:** 114772 - 00  
**Change Title:** Intel® Server Chassis H2216XXKR2  
PCN 114772 - 00,  
Product Material, Front panel bezel  
**Date of Publication:** July 13, 2016

## Key Characteristics of the Change:

Front Panel bezel material change

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material *:</b>	July 25, 2016
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*\* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.*

## Description of Change to the Customer:

Intel is implementing the following change on the Intel® Server Chassis H2216XXKR2:

1. Change the housing mini-FP bezel material from plastic to die-cast to align with the Intel® Server Chassis H2224XXKR2 mini-FP bezel.

Figure 1. mini-FP bezel (Left and Right) post-change



**Customer Impact of Change and Recommended Action:**

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

**Products Affected / Intel Ordering Codes:**

<b>Product Code</b>	<b>MM#</b>	<b>Pre Change TA</b>	<b>Post Change TA</b>
H2216XXKR2	933688	H20866-006	H20866-007

**PCN Revision History:**

**Date of Revision:**

June 13, 2016

**Revision Number:**

00

**Reason:**

Originally Published PCN



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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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